

Enrollment No./Seat No.:

**GUJARAT TECHNOLOGICAL UNIVERSITY**  
**Bachelor of Engineering - SEMESTER - VI EXAMINATION - SUMMER 2025**

**Subject Code: 3160004**

**Date: 26-05-2025**

**Subject Name: Fundamental of Semiconductor Package Manufacturing and Test**

**Time: 10:30 AM TO 01:00 PM**

**Total Marks: 70**

**Instructions**

- 1. Attempt all questions.**
- 2. Make suitable assumptions wherever necessary.**
- 3. Figures to the right indicate full marks.**

	<b>Marks</b>
<b>Q.1 (a)</b> List out any 3 package types from each category for common, advanced, and emerging package types	<b>03</b>
<b>(b)</b> What is Semiconductor Packaging? Why is it needed?	<b>04</b>
<b>(c)</b> What is Encapsulation Process? What is its purpose? List down different types of encapsulation technique?	<b>07</b>
<b>Q.2 (a)</b> What is Gage Repeatability & Reproducibility?	<b>03</b>
<b>(b)</b> What is Burn In Test ? Draw the Burn Bath tub curve ?	<b>04</b>
<b>(c)</b> What are the limitations of 2D NAND ? What is the Advantage of 3D NAND ?	<b>07</b>
<b>OR</b>	
<b>(c)</b> What is Parametric Testing? And why do we collect Parametric Testing data ?	<b>07</b>
<b>Q.3 (a)</b> What does it means by TAL (time above liquid) in reflow profile?	<b>03</b>
<b>(b)</b> What is DAF? Explain in detail its major ingredients.	<b>04</b>
<b>(c)</b> Explain the manufacturing process of organic substrates.	<b>07</b>
<b>OR</b>	
<b>(a)</b> Describe reliability testing.	<b>03</b>
<b>(b)</b> Explain Storage life test(SLT).	<b>04</b>
<b>(c)</b> Describe 5 EMC ingredients and briefly explain its purposes	<b>07</b>
<b>Q.4 (a)</b> Write working and application of Time domain reflectometer (TDR).	<b>03</b>
<b>(b)</b> Draw and explain the schematic for Basic FA(Failure analysis) Flow	<b>04</b>
<b>(c)</b> How 3D X-ray technique is different compared to 2D-Xray technique?	<b>07</b>
<b>OR</b>	
<b>(a)</b> List down Physical failure analysis (PFA) techniques	<b>03</b>
<b>(b)</b> What is a Curve Tracer and what are its applications?	<b>04</b>
<b>(c)</b> What is Failure analysis? What are the broad categories of semiconductor device fails?	<b>07</b>

- Q.5 (a)** List different methods for ranking risks. **03**
- (b)** What are some of the differences between Design FMEA (DFMEA) and Process FMEA (PFMEA) **04**
- (c)** What are the roles of leaders and employees in implementing QMS and what are the benefits of implementing Quality Management System? **07**

**OR**

- (a)** Why Statistical Process Control is important in industry? **03**
- (b)** Describe the difference between Issues and Risks. Describe how FMEA helps mitigate Risks and prevents Issues. **04**
- (c)** Explain how cost of quality can help an organization improve its business performance and customer satisfaction. Provide examples of prevention, appraisal, internal failure, and external failure costs in your answer. **07**

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